

[METHOD OF ASSEMBLING PASSIVE COMPONENT]

Abstract

A method of assembling a passive component over the active surface of a die is provided. The method shortens the signal transmission path between the die and the passive component so that electrical performance of the die after packaging is improved. In addition, the transmission path and the number of contacts on the substrate for connecting the die and the passive component are reduced. With a reduction in transmission path, size of the substrate can be reduced. Furthermore, a plurality of passive components may be assembled onto the dies of a wafer in a single operation so that there is no need to assemble individual passive component over each packaging substrate.